

CLAIMS

1. An apparatus for enclosing a logic chip, comprising:
a substrate having a surface adapted to receive the logic chip mounted thereon;
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a mold cap disposed upon said substrate, said mold cap extending at least partially
over said logic chip and including at least one extension of a preselected
size and shape extending at least partially into a corner section of said
substrate.
- 10 2. The apparatus of claim 1, wherein said extension is a rib structure.
3. The apparatus of claim 1, wherein said extension is a radiused structure.
- 15 4. The apparatus of claim 1, wherein said extension comprises a full radius
corner of said mold cap.
5. The apparatus of claim 1, including a plurality of solder balls positioned
on a bottom surface of the substrate spaced from an edge of the logic chip.
- 20 6. A plastic ball grid array assembly comprising:
a substrate having a generally polygon shape defining at least one corner section;

12. The method, as set forth in claim 11, wherein the act of forming a mold cap includes forming a rib structure extending into said corner section of said substrate.

13. The method, as set forth in claim 11, wherein the act of forming a mold cap includes forming a radiused structure extending into said corner section of said substrate.

14. The method, as set forth in claim 11, wherein the act of forming a mold cap includes forming a full radius corner extending into said corner section of said substrate.

15. The method, as set forth in claim 11, including placing a plurality of solder balls on a bottom surface of the substrate placed from an edge of the logic chip.

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